

Desmear/Electroless Copper for Semi Additive Process

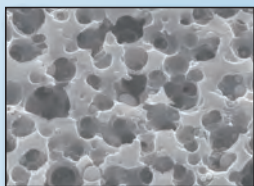
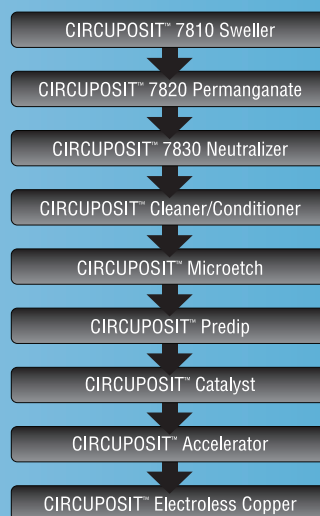
除胶渣及化学沉铜技术应用于半加成制程

CIRCUPOSIT™ 7800 Electroless Copper

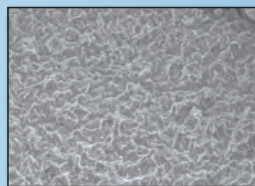
Features and Benefits 特性及优点

- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning
能提升均匀且稳定的表面结合能力及对于盲孔孔底有可靠的清洁能力
- Stable and wide process window
操作范围大且表现稳定
- High peel strength and optimum surface roughness for insulator adhesion
抗拉扯强度高, 对于绝缘层的贴合表面有最理想的粗糙度
- Excellent plating coverage of electroless copper on insulator and especially on via bottom
优越的镀层覆盖能力, 使化学沉铜均匀地覆盖在绝缘层表面及盲孔底部
- Excellent electrical reliability with high insulation resistance
在高度的绝缘阻抗下能表现出卓越的信赖性
- Provide great foundation for fine line solution
为细线路解决方案提供最佳基础

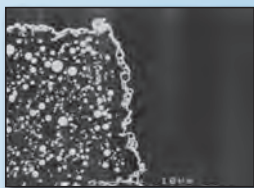
Process 製程



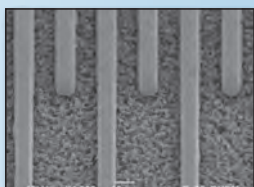
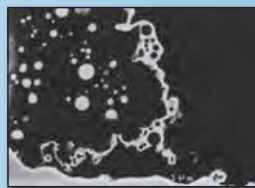
Adhesion promotion on insulator



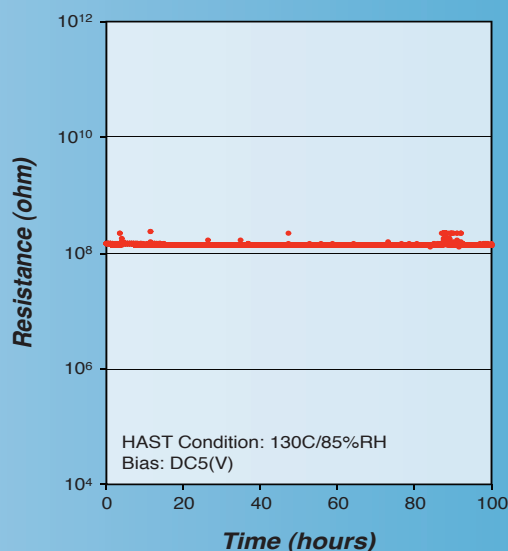
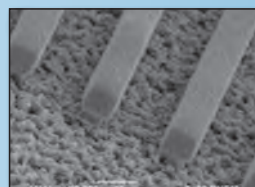
Via bottom cleaning



Excellent plating coverage on insulator and via bottom



Fine line capability (L/S = 10/10 μm ultra fine line of ABF GX13)



Excellent reliability performance (by migration test on 10/10 μm)

